

# 承认书

## SPECIFICATION FOR APPROVAL

客户 Customer	:	
客户批号 Customer Part No.	:	
型号 Part No.	:	K3535P15KOMZ003 K3535P15KOMZ005 K3535P15KOMZ006
制作人 Prepared By	:	日期 Time: 2020/05/19
审核 Checkedy	:	日期 Time: 2020/05/19
客户回签 Customer Comfirmation	:	日期 Time:

客户意见栏 ( Customer' S Proposal)

Approve 承认 (请于认可栏中签名)       Disagree 不同意

Reason 原因: \_\_\_\_\_

版本 ( Version):   1.3

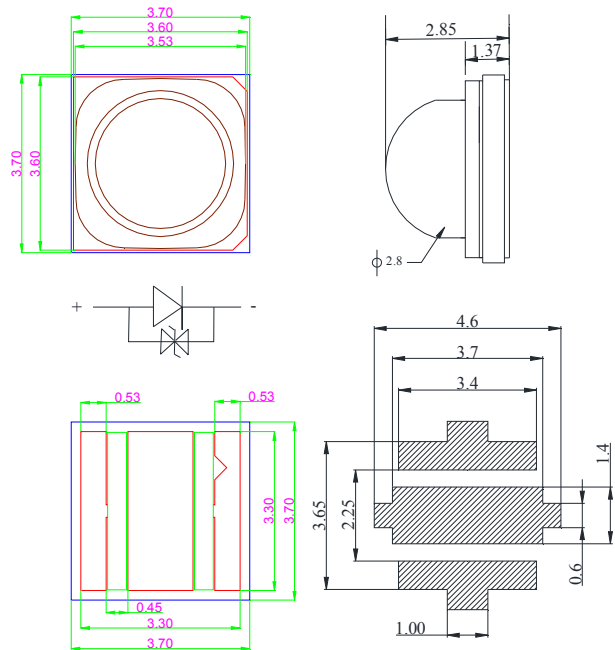
● **Features:**

1. Emitted Color: UVA
2. Lens Appearance: Clean quartz lens
3. 3.7x3.7x2.85mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● **Applications:**

1. UV Curing

● **Package Dimensions:**



NOTES:

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.10$ mm unless otherwise specified.
3. Specifications are subject to change without notice.

● **Part Numbering System:**

<b><u>K</u></b>	<b><u>3535</u></b>	<b><u>P1</u></b>	<b><u>5K</u></b>	<b><u>0</u></b>	<b><u>M</u></b>	<b><u>003</u></b>
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- (1) N : Substrate code
- (2) Package type: 3535
- (3) LED Color: P1 means UV segment
- (4) Chip code
- (5) 0:CRI not required
- (6) M:Type of Silicon
- (7) 003:Color bin



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

● Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Power Dissipation	PD	5	W
DC Forward Current	IF	700	mA
Single Chip Pulsed Forward Current	IFP	1000※	mA
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-30 ~ +80■	°C
Storage Temperature	Tstg	-40 ~ +120	°C
Soldering Temperature	Tsol	260for5sec△	°C

※Duty 1/10, Pulse Width 0.1ms.

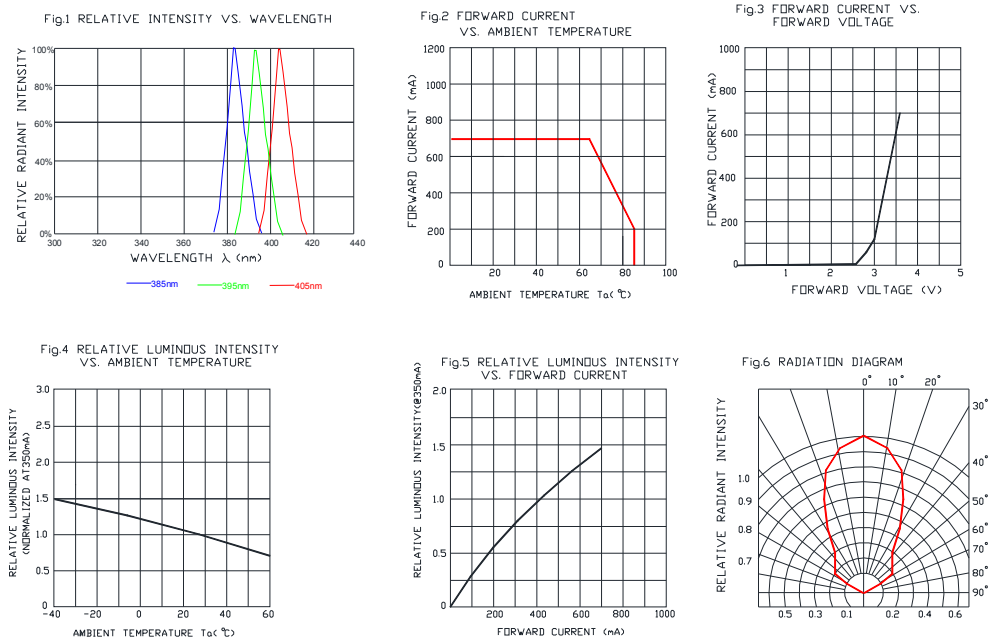
△Soldering time max 10sec

■please refer to IF-Ta diagram of curves for the temperature during application

● Parameter

Parameter	Symbol	Value			Unit	Test condition
		Min.	Typ.	Max		
Forward Voltage	Vf	-	3.5	-	V	If=700mA
Reverse Current	Ir	-	-	10	μA	Vr=5V
Viewing angle	2θ1/2	-	60	-	Deg	If=700mA
Peak Wavelength	λp	380	385	390	nm	If=700mA
Luminous Power	Po	-	1200	-	mw	If=700mA
Peak Wavelength	λp	390	395	400	nm	If=700mA
Luminous Power	Po	-	1200	-	mw	If=700mA
Peak Wavelength	λp	400	405	410	nm	If=700mA
Luminous Power	Po	-	1200	-	mw	If=700mA

● Typical Electro-Optical Characteristics Curves



## ● Soldering :

### 1. Manual Soldering

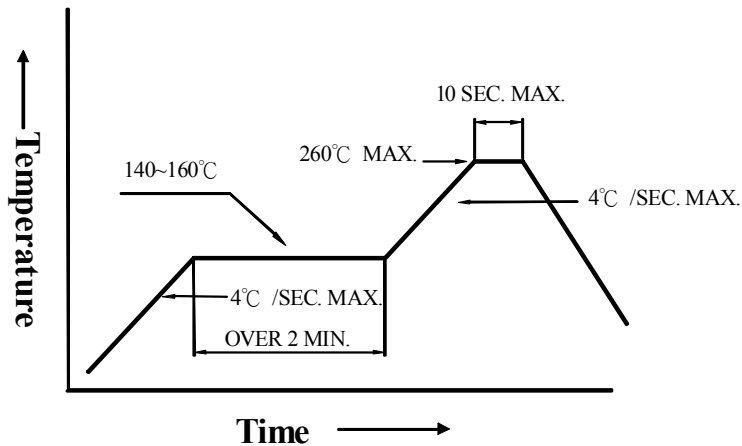
The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

### 2. Reflow Soldering

Preheating : 140°C~160°C±5°C, within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds. (Max)

Gradual Cooling (Avoid quenching).



## ● Lens cleaning

In the case where a minimal level of dirt and dust particles can not be guaranteed, a suitable cleaning solution can be applied to the lens surface

1. Try a gentle swabbing using a lint-free swab
2. If needed, the use of lint-free swab and isopropyl alcohol used gently removes dirt from the lens surface
3. Do not use other solvents as they may directly react with the LED assembly
4. Do not use ultrasonic cleaning that the LED will be damaged

## ● Carrier Tape Handling

The following items are recommended when handling the Carrier tape of LEDs

1. Do not twist the carrier tape
2. The inward bending diameter should not smaller than 6cm for carrier tape.
3. Do not bend the tape outward.
4. Storage temperature should not exceed 60°C



● **Handling :**

Care must be taken not to damage LED's silicon while exposing to high temperature or contact LED's epoxy resin with hard or sharp objects, such as metal hook, tweezer or sand blasting.

● **Storage:**

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C(41°F) Humidity : RH 60 % Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
  - a. Completed within 168 hours.
  - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
  - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:  
48 hours at 60°C±3°C.

● **Package and Label of Products:**

- (1) Package: Products are packed in one bag of 500 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

Part No. : XXXXXXXXX  
Type No. : E-XXXX-XX-XX-XX-XXX  
VF(1000mA) : XX-XX  
IV(1000mA) : XXXX-XXXX  
CCT(1000mA): XXXX-XXXX  
Q'TY : XXXXPCS  
Lot No. : X-XXX-XX-X

● **Tapping and packaging specifications (Units: mm)**

